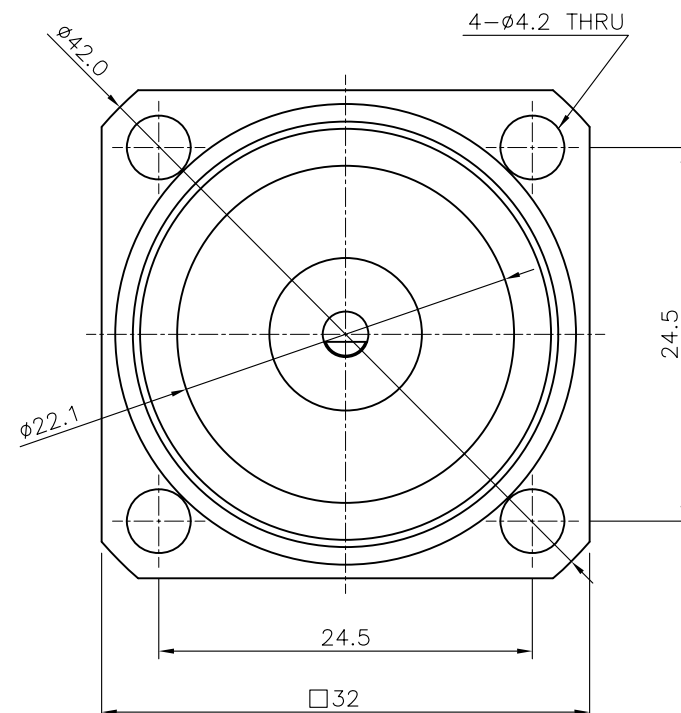
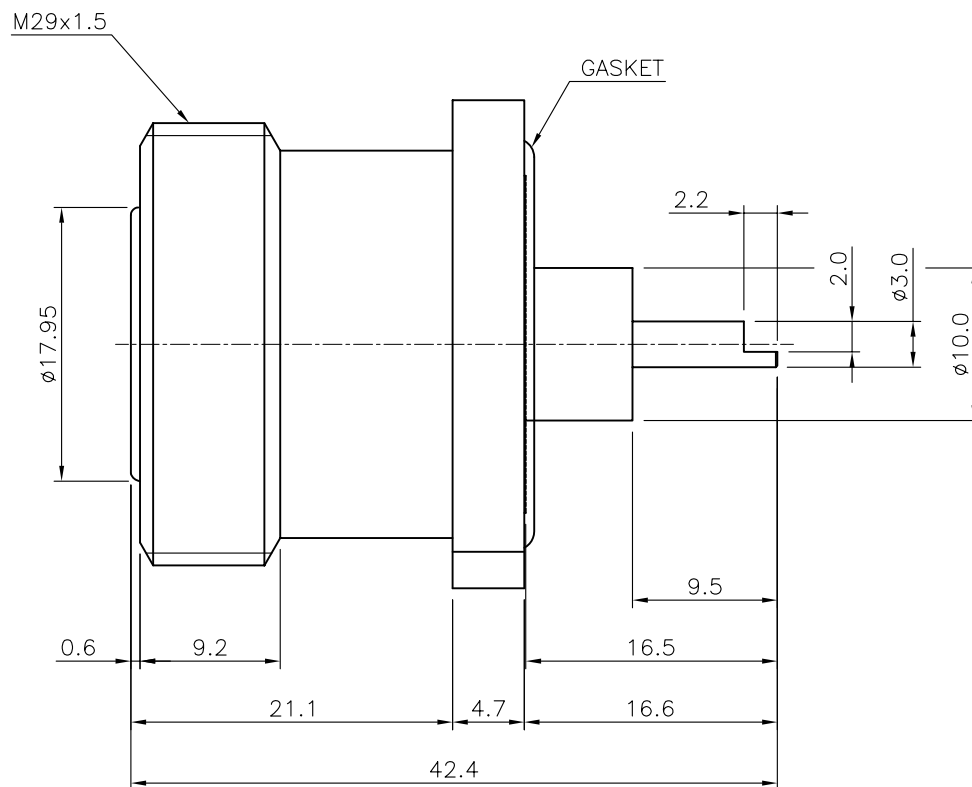


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	I.C.KIM	Y.H.CHOI	2011.03.28.
1	[설번처리No.201104-0002] C-RING 및 PIN 안착부 길이 변경	I.C.KIM	Y.H.CHOI	2011.04.18.
2	[설번처리No.201307-0005] 원가절감 (C-RING 재변경 - PIN 안착부 길이 변경)	E.H.KIM	I.C.KIM	2013.07.12.



2	1	5	SPRING RING	1	BeCu	Silver Plate 7μm	DSR01054-5/2
		4	INSULATOR	1	TEFLON		DIN01889-N/1
		3	GASKET	1	SILICONE RUB		DGK00199-N/1
2	1	2	CONTACT	1	MBsBD	Silver Plate 7μm	DCT02418-5/1
		1	BODY	1	MBsBD	SUCO Plate (3μm)	DBD02896-5/1
NO.		DESCRIPTION		Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE			 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	±0.1	2013. 07. 12.			
	Angle	APPROVED BY	I.C.KIM		KJ COMTECH CO.,LTD.
	±1°	CHECKED BY			
MATERIAL	_____	DRAWN BY	E.H.KIM		TITLE
FINISH	_____	SCALE	UNIT		7/16 DIN50 SOLDER END JS-4H
		2/1	mm		A4
					DWG NO. CN02653-7/1
					REVISION 2 SHEET 1 of 1

주 기

1. □ 32 4면 엔드밀 작업시 적용 치수 (□32~□31.6)